



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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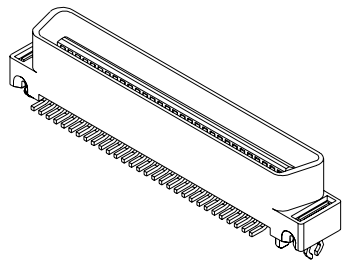
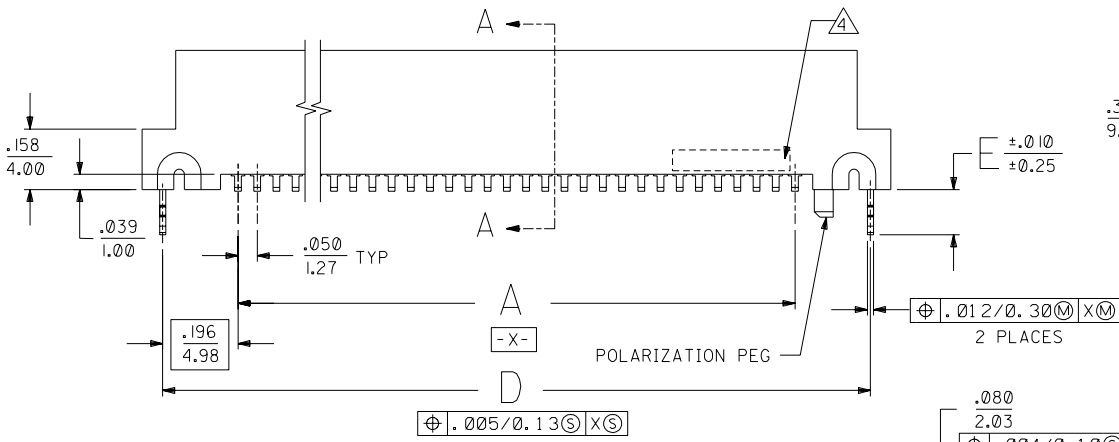
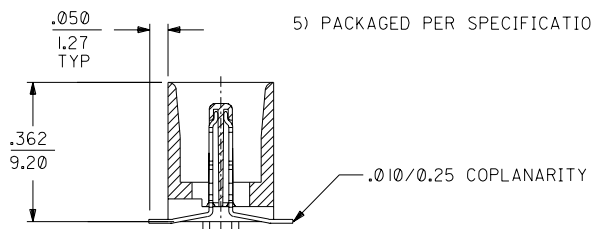
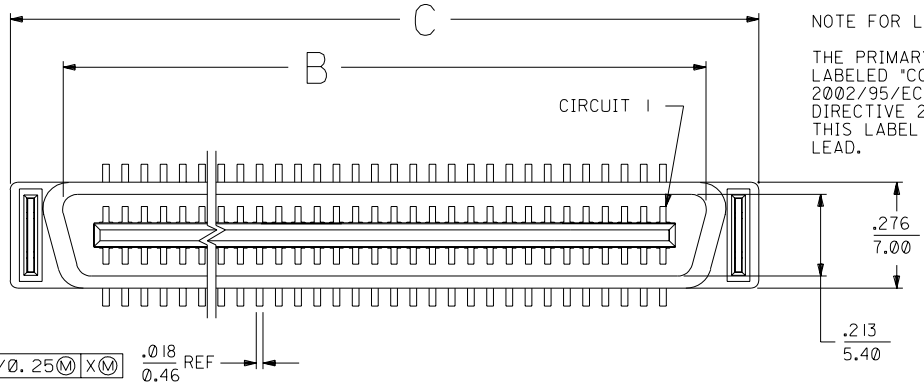


NOTE FOR LEAD FREE CONVERSION:

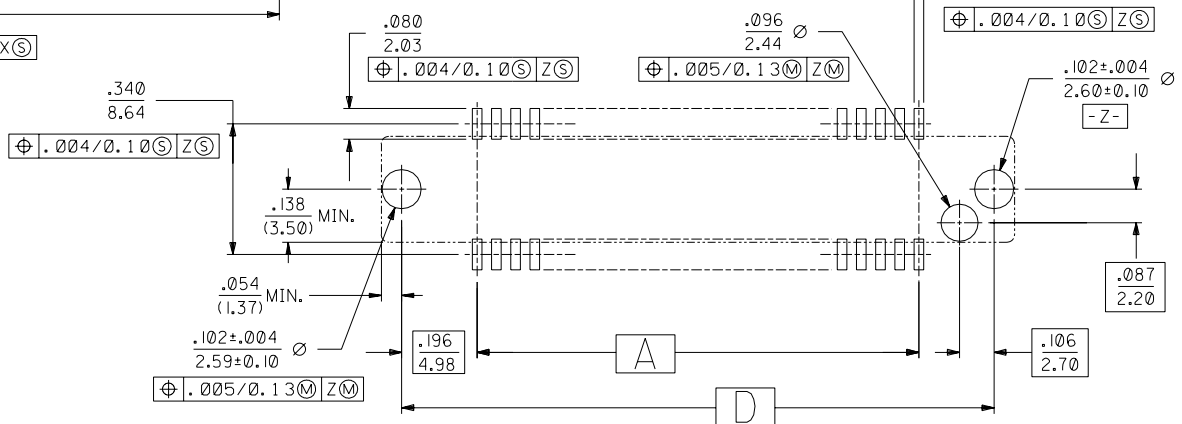
THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO ROHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.

NOTES:

- 1) MATERIALS:
HOUSING: I.R. COMPATIBLE POLYMER, GLASS FILLED, UL 94 V 0, BLACK
TERMINALS: BRASS
BOARDLOCK: PHOSPHOR BRONZE
- 2) PLATING:
.000030/(0.00076) MINIMUM GOLD IN CONTACT AREA AND
.000050/(0.00127) MINIMUM TIN IN TAIL AREA OVER
.000075/(0.00191) MINIMUM NICKEL UNDERPLATING OVERALL.
- 3) ASSEMBLY MATES WITH MOLEX P/N SDA-71660-****, CONFORMS TO PRODUCT SPECIFICATION PS-71660.
- 4) FOUR DIGIT DATE CODE (WK, YR), EXAMPLE => 26 96 LOCATED IN AREA INDICATED.
- 5) PACKAGED PER SPECIFICATION PK-70873-055.



60 CIRCUIT ASSEMBLY SHOWN
SCALE = 2:1



J	LEAD FREE CONV ECN UCP2004-2096 RKADAMS 04/04/23
I	CHANGE PK SPEC ECN UCP2004-0922 RWHITE 03/11/11
H	ADD -5069 & -5100 ECN UCP2003-1596 RWHITE 03/02/06
G	REV PACKAGING ECN UDT2000-1183 ACHAMMER 00/05/30
F	REVISED PER ECN UDT1999-1036 KSMITH 99/05/26
E	REVISED PER ECN U71132 RESENDEZ 97/3/21
D2	REVISED PER ECN U70871 ACHAMMER 97/2/3
D1	REVISED PER ECN U70444 ACHAMMER 96/10/17
D	REVISED PER ECN U60641 11-28-95 DRS
C	REVISED PER ECN U50830 2-24-95 RAN
B	REVISED PER ECN U40901 7-20-94 RAN
A	INITIAL RELEASE PER ECN U40378 3-18-94 RAN

71661-5100	100	.062±.006 (1.57±0.15)	2.450 (62.23)	2.676 (67.97)	2.949 (74.90)	2.842 (72.19)	.118 (3.00)
71661-5080	80	.062±.006 (1.57±0.15)	1.950 (49.53)	2.176 (55.27)	2.449 (62.20)	2.342 (59.50)	.118 (3.00)
71661-5069	68	.116±.006 (2.95±0.15)	1.650 (41.91)	1.875 (47.65)	2.149 (54.58)	2.042 (51.88)	.172 (4.37)
71661-5068	68	.062±.006 (1.57±0.15)	1.650 (41.91)	1.875 (47.65)	2.149 (54.58)	2.042 (51.88)	.118 (3.00)
71661-5060	60	.062±.006 (1.57±0.15)	1.450 (36.83)	1.676 (42.57)	1.949 (49.50)	1.842 (46.80)	.118 (3.00)
71661-5050	50	.062±.006 (1.57±0.15)	1.200 (30.48)	1.426 (36.22)	1.699 (43.15)	1.592 (40.45)	.118 (3.00)
71661-5040	40	.062±.006 (1.57±0.15)	.950 (24.13)	1.176 (29.87)	1.449 (36.80)	1.342 (34.10)	.118 (3.00)
71661-5031	30	.116±.006 (2.95±0.15)	.700 (17.78)	.925 (23.52)	1.199 (30.45)	1.092 (27.75)	.172 (4.37)
71661-5030	30	.062±.006 (1.57±0.15)	.700 (17.78)	.925 (23.52)	1.199 (30.45)	1.092 (27.75)	.118 (3.00)

ITEM NUMBER	CIRCUIT SIZE	RECOMMENDED CIRCUIT BOARD THICKNESS	A	B	C	D	E
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MFG, SH, REV, LTR, REVISIONS

SALES ASSEMBLY
MOLEX EBB1 50D SMT
PLUG CONNECTOR

MOLEX INCORPORATED
LITSE, ILL. 60532 U.S.A.

DATE 2/1/93

SEE TABLE SDA-71661-5***

DRWG. BY RAN CHK'D BY RAN
APP'D BY CAB SCALE 4:1

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